

RD3H045SP

Pch -45V -4.5A Power MOSFET

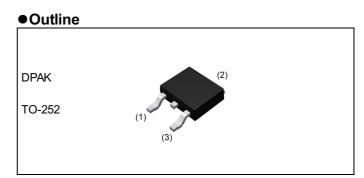
V _{DSS}	-45V
R _{DS(on)} (Max.)	155mΩ
Ι _D	±4.5A
P _D	15W

Features

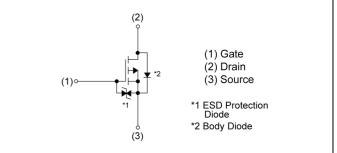
Application

Switching

- 1) Low on resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating ; RoHS compliant



●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
_	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2500
	Taning and	TL
	Taping code	TL1
	Marking RD3H04	

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

C (u	1 ,		
Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	-45	V
Continuous drain current	I _D *1	±4.5	А
Pulsed drain current	I _{DP} *2	±9.0	А
Gate - Source voltage	V _{GSS}	±20	V
Power dissipation	P _D *3	15	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

•Thermal resistance

Deremeter	Sumbol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}^{*3}	-	-	8.33	°C/W

• Electrical characteristics (T_a = 25°C)

Deverseter	Currente e l	Canditiana	Values			1.1:4
Parameter	Parameter Symbol Conditions		Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = -1mA$		-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}} I_{D} = -1 mA$ referenced to 25°C		-50	-	V/°C
Zero gate voltage drain current	I _{DSS}	V _{DS} = -45V, V _{GS} = 0V	-	-	-1	μA
Gate - Source leakage current	I _{GSS}	I_{GSS} V_{GS} = ±20V, V_{DS} = 0V		-	±10	μA
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = -10V , I _D = -1mA	-1.0	-	-3.0	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	3.3	-	V/°C
		V _{GS} = -10V, I _D = -4.5A	-	110	155	
Static drain - source on - state resistance	R _{DS(on)} *4	V _{GS} = -4.5V, I _D = -4.5A	-	160	225	mΩ
		V _{GS} = -4.0V, I _D = -4.5A	-	185	260	
Gate resistance	R_{G}	f = , open drain	-	7.7	-	Ω
Forward Transfer Admittance	Y _{fs} ^{*4}	V _{DS} = -10V, I _D = -4.5A	3.0	-	-	S

*1 Limited only by maximum temperature allowed.

*2 Pw \leq 10µs , Duty cycle \leq 1%

*3 T_C=25°C

*4 Pulsed



• Electrical characteristics ($T_a = 25^{\circ}C$)

Deremeter	Cumphol	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	550	-	
Output capacitance	C _{oss}	V _{DS} = -10V	-	100	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	50	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq -25V, V_{GS} = -10V$	-	8	-	
Rise time	t _r *4	I _D = -2A	-	8	-	20
Turn - off delay time	$t_{d(off)}^{*4}$	$R_L \simeq 12.5\Omega$	-	35	-	ns
Fall time	t _f *4	R _G = 10Ω	-	8	-	

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q_g^{*4}	עם ≃ -2 5V,	-	12	-	
Gate - Source charge	Q _{gs} *4	V _{DD} ≃ -25V, I _D = -4.5A,	-	2.2	-	nC
Gate - Drain charge	${\sf Q}_{\sf gd}{}^{*4}$	V _{GS} = -5V	-	2.2	-	

•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ _S *1	T - 25°0	-	-	-4.5	А
Pulse forward current	I_{SP}^{*2}	T _a = 25°C	-	-	-9.0	А
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = -4.5A	-	-	-1.2	V



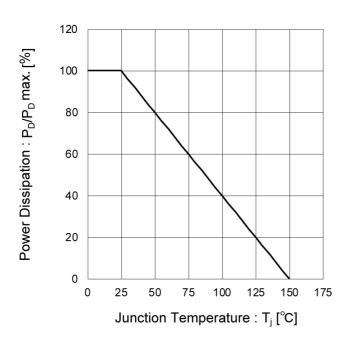


Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

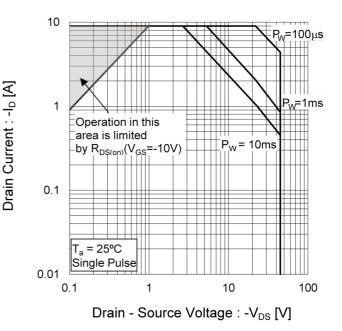
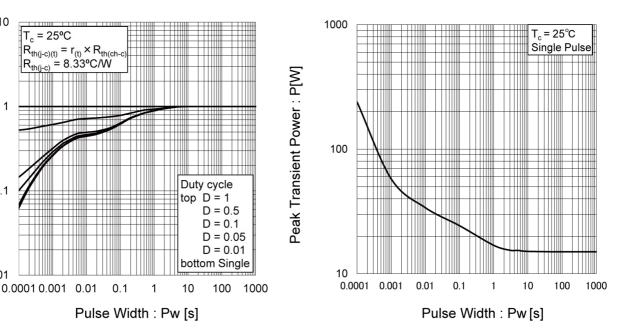


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power dissipation



10

1

0.1

0.01

= 25°C

R_{th(j-c)}

Normalized Transient Thermal Resistance : r(t)



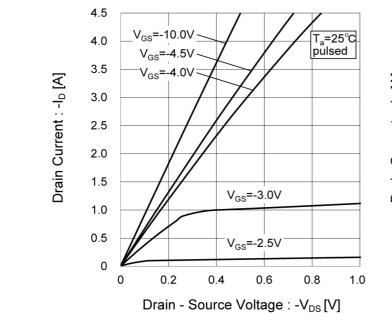


Fig.5 Typical Output Characteristics(I)

Fig.6 Typical Output Characteristics(II)

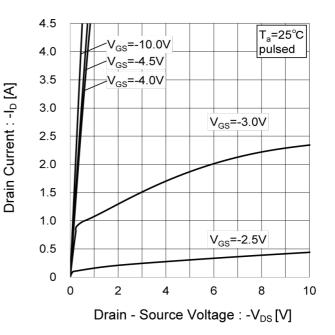
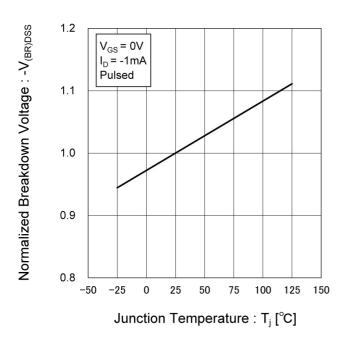


Fig.7 Breakdown Voltage vs. Junction Temperature





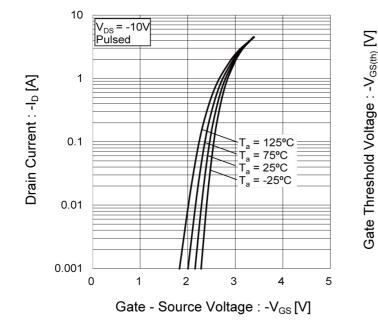


Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature

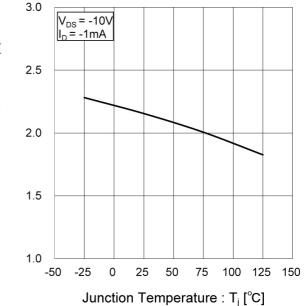
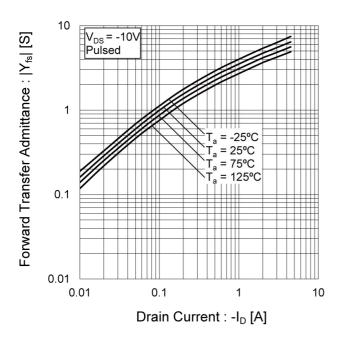


Fig.10 Forward Transfer Admittance vs. Drain Current





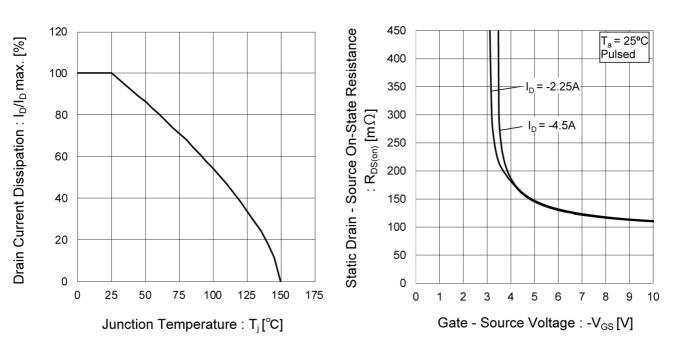
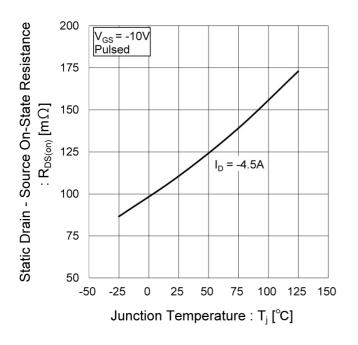


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature







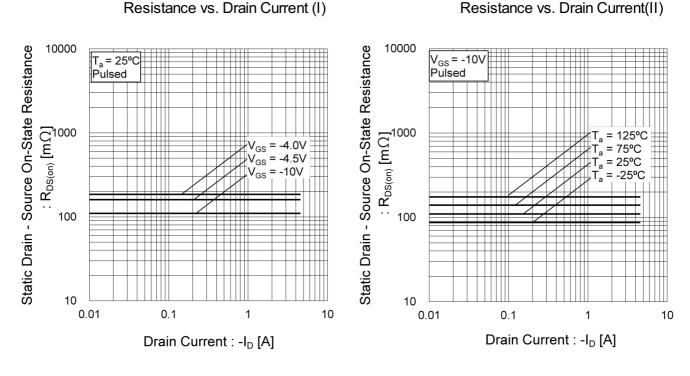


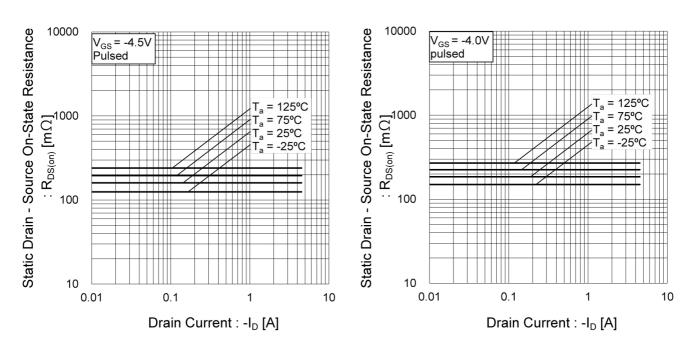
Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

Fig.16 Static Drain - Source On - State

Resistance vs. Drain Current(III)

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

Fig.15 Static Drain - Source On - State





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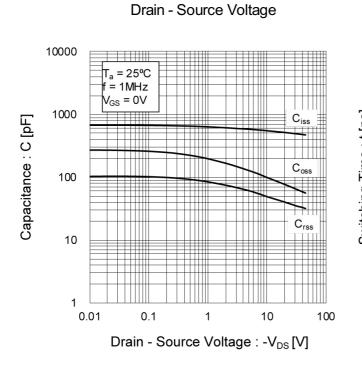


Fig.18 Typical Capacitance vs.

Fig.19 Switching Characteristics

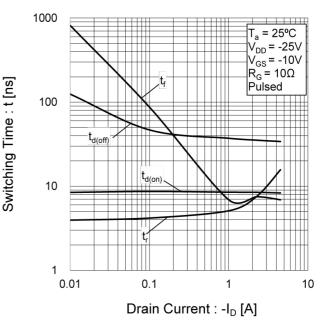


Fig.20 Dynamic Input Characteristics

Gate - Source Voltage : -V_{GS} [V]

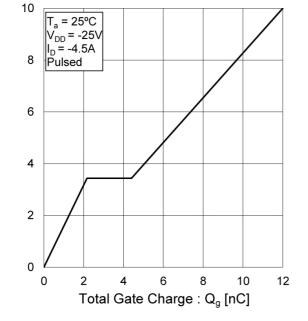
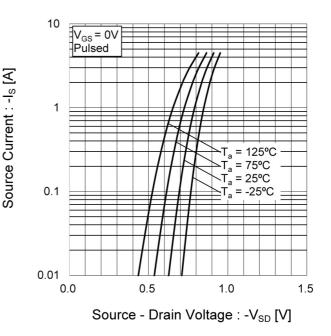


Fig.21 Source Current vs. Source Drain Voltage





Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

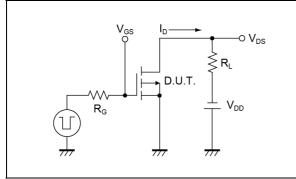


Fig.2-1 Gate Charge Measurement Circuit

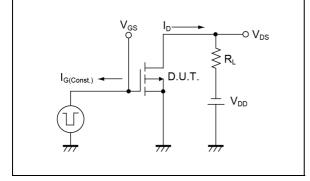
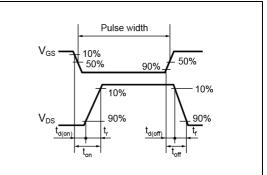
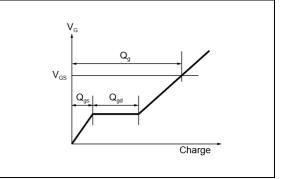


Fig.1-2 Switching Waveforms

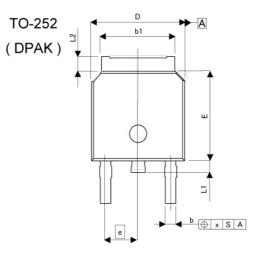


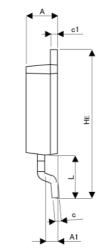


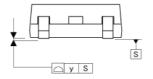


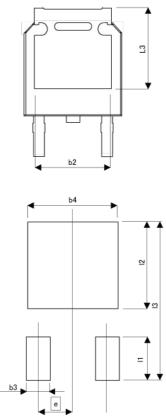


$\bullet \textit{Dimensions}(\mathsf{TL})$









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

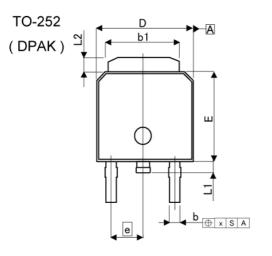
DIM	MILIME	TERS	INCHES	
DIVI	MIN	MAX	MIN	MAX
A	2.10	2.30	0.083	0.091
A1	0.70	1.10	0.028	0.043
b	0.65	0.85	0.026	0.033
b1	5.10	5.40	0.201	0.213
b2	5.	10	0.2	01
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.0	91
Е	6.00	6.40	0.236	0.252
HE	9.50	10.50	0.374	0.413
L	2.90		0.114	
L1	0.70	0.90	0.028	0.035
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.209	
х	-	0.10	-	0.004
у	-	0.10	-	0.004
		TEDO	INICI	100

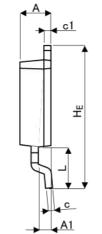
DIM	MILIMETERS		INCH	IES
Divi	MIN	MAX	MIN	MAX
b3	-	1.10	2 C	0.043
b4	-	5.40	-	0.213
11	-	2.90	-	0.114
12	-	5.50	3 - 3	0.217
13	-	10.50	-	0.413

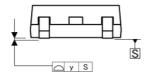
Dimension in mm/inches

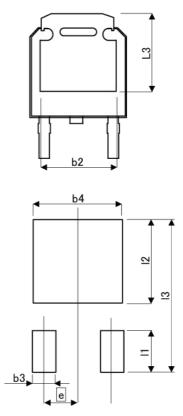


• Dimensions (TL1)









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	TERS	INCHES		
DIN	MIN	MAX	MIN	MAX	
A	2.20	2.40	0.087 0.094		
A1	0.70	1.10	0.028	0.043	
b	0.60	0.90	0.024	0.035	
b1	5.20	5.50	0.205	0.217	
b2	5.	35	0.2	211	
С	0.40	0.60	0.016	0.024	
c1	0.40	0.60	0.016	0.024	
D	6.40	6.80	0.252	0.268	
е	2.	30	0.0	91	
E	6.00	6.40	0.236	0.252	
HE	9.40	10.40	0.370	0.409	
L	2.	70	0.106		
L1	0.60	1.00	0.024	0.039	
L2	0.70	1.30	0.028	0.051	
L3	5.	30	0.209		
х	-	0.25	-	0.010	
У	-	0.10	-	0.004	
DIM	MILIME	TERS	INCHES		
	MIN	MAX	MIN	MAX	
b3		1.15	2	0.045	
b4	-	5.55	-	0.219	
1	-	2.77	-	0.109	

Dimension in mm/inches

12 13 5.50 10.40



0.217

Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ		CLASSⅢ	

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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RD3H045SP - Web Page

Distribution Inventory

Part Number	RD3H045SP
Package	TO-252
Unit Quantity	2500
Minimum Package Quantity	2500
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes